

AD177A0 Datasheet

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Version: 1.0

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AD177A0 Features

CPU

- 32bit DSP
- Maximum speed 160MHz
- Interrupts with 8 priority level

Memory

- Optional built-in flash memory

Clocks

- On-chip 16 MHz clock
- On-chip 200KHz lower-temperature-drift clock

Audio APA

- Support for driving 4 or 8 ohm speaker
- Mono Class-D Speaker Amplifier
 - 0.42W/8 Ω @3.7V
 - 0.17W/8 Ω @2.4V
 - 0.62W/4 Ω @3.7V
 - 0.25W/4 Ω @2.4V

Peripherals

- Three multi-function 16-bit timers, support capture and PWM mode
- Two UART Controllers(UART0/1) supports DMA and Flow Control
- One IIC Master controller

- Two SPI Master / Slaver controller with DMA
 - SPI0 support 4bit,SPI1 support 2bit
- 16-channel 10-bit general purpose ADC
- 4-channel Advance PWM controller
- 21 Individually programmable and multiplexed GPIO pins
- Digital peripheral crossbar
- Up to 12 external interrupt / wake-up source (low power available,can be multiplexed to any I/O)
- Watchdog

PMU

- Less than 2uA soft off current
- VBAT range : 2.0V to 5.5V
- HPVDD range : 2.0V to 5.5V
- IOVDD range : 2.0V to 3.4V

Packages

- QSOP28

Temperature

- Operating temperature: -40°C to +85°C
- Storage temperature: -65°C to +150°C

Applications

- Sound Toy
- Audio player
- Universal Microcontroller

1 Block Diagram

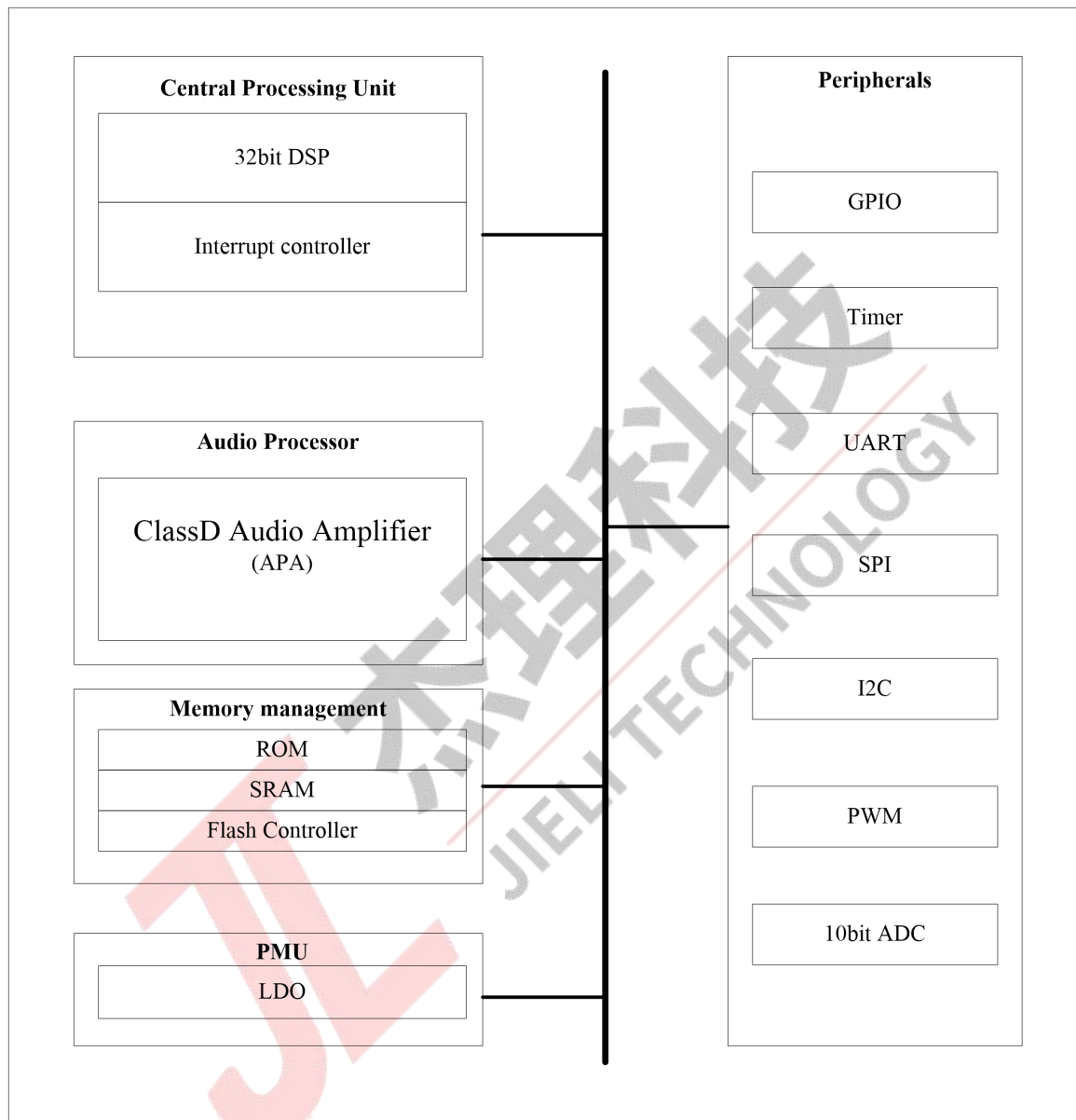


Figure 1-1 AD177A0 Block Diagram

2.2 Pin Description

Table 2-1 AD177A0 Pin Description

PIN NO.	Name	Type	Function	Other Function
1	PB3	I/O	5V tolerant IO	
2	PB2	I/O	5V tolerant IO (pull up)	MCLR:Low level reset; APA_DON;
3	PB1	I/O	5V tolerant IO	Serial port code upgrade pin; APA_DOP;
4	PB0	I/O	5V tolerant IO	
5	PA12	I/O	GPIO	ADC12:ADC Input Channel 12; PWMFP1;
6	PA11	I/O	GPIO	ADC11:ADC Input Channel 11; PWMFP0;
7	PA10	I/O	GPIO	ADC10:ADC Input Channel 10;
8	PA9	I/O	GPIO (pull down)	ADC9:ADC Input Channel 9; Touch cap; CLK OUT2:Internal clock output2;
9	PA8	I/O	GPIO (pull down)	ADC8:ADC Input Channel 8; SPI1DI:SPI1 Data In; WKUP; CLK OUT1:Internal clock output1;
10	PA7	I/O	GPIO (pull down)	ADC7:ADC Input Channel 7; SPI1DO:SPI1 Data Out; UART1RX:Uart1 Data Input; EXTCLK:External clock source; CLKOUT0:Internal clock output0;
11	PA6	I/O	GPIO (pull down)	ADC6:ADC Input Channel 6; SPI1CLK:SPI1 Clk; UART1TX:Uart1 Data Output;
12	PD2	I/O	GPIO	SFCCS:SFC Chip Select;
13	PD3	I/O	GPIO	SFCDI:SFC Data In; ADC14:ADC Input Channel 14;
14	FSPG	O	(pull down)	Flash Power Gate; ADC15:ADC Input Channel 15;
15	PD0	I/O	GPIO	SFCCLK:SFC Clk;
16	PD1	I/O	GPIO	SFCDO:SFC Data Out; ADC13:ADC Input Channel 13;
17	PA5	I/O	GPIO	ADC5:ADC Input Channel 5; PWMCK1; UART1 CTS:Uart1 clear to send; UART1 RTS:Uart1 request to send;

18	PA4	I/O	GPIO	ADC4:ADC Input Channel 4; PWMCK0; SPI0D3:SPI0 Data 3; UART0RX:Uart0 Data Input; PWMCH1H:Motor PWM Channel1(H);
19	PA3	I/O	GPIO	ADC3:ADC Input Channel 3; SPI0D2:SPI0 Data 2; UART0TX:Uart0 Data Output; PWMCH1L:Motor PWM Channel1(L); CAP0:Timer0 Capture; CAP2:Timer2 Capture; PWM0:Timer0 PWM Output;
20	PA2	I/O	GPIO	ADC2:ADC Input Channel 2; SPI0DI(1):SPI1 Data In(1); TMR0:Timer0 Clock Input; TMR2:Timer2 Clock Input; PWM2:Timer2 PWM Output;
21	PA1	I/O	GPIO	ADC1:ADC Input Channel 1; SPI0DO(0):SPI0 Data Out(0); I2C SDA; PWMCH0H:Motor PWM Channel0(H); CAP1:Timer1 Capture; LVD:Low Voltage Detect;
22	PA0	I/O	GPIO (pull up)	Long press reset; ADC0:ADC Input Channel 0; SPI0CLK:SPI0 Clk; I2C SCL; TMR1:Timer1 Clock Input; PWM1:Timer1 PWM Output; PWMCH0L:Motor PWM Channel0(L);
23	VSS	G		System ground;
24	IOVDD	PO	Power supply for GPIO	Built-in linear voltage regulator output;
25	VBAT	PI		Power supply input;
26	HPVDD	PI		Class-D APA Power supply;
27	APAP	O		Class-D APA Positive Output;
28	APAN	O		Class-D APA Negative Output;

Pin Type	Description	Pin Type	Description
P	Power	I/O	Input or Output
PI	Power Input	I	Input
PO	Power Output	O	Output
AO	Analog Output	G	Ground

3 Electrical Characteristics

3.1 Absolute Maximum Ratings

Table 3-1

Symbol	Parameter	Min	Max	Unit
T _{opt}	Operating temperature	-40	+85	°C
T _{stg}	Storage temperature	-65	+150	°C
V _{BAT}	Supply Voltage	-0.3	6	V
HPVDD	APA Power supplyVoltage	-0.3	6	V
V _{IOVDD}	Voltage applied at IOVDD	-0.3	3.6	V
V _{GPIO}	Voltage applied to GPIO	-0.3	IOVDD+0.3	V
V _{HVIO}	Voltage applied to High Voltage Resistant IO	-0.3	+5.5	V

Note : The chip can be damaged by any stress in excess of the absolute maximum ratings listed below

3.2 PMU Characteristics

Table 3-2

Symbol	Parameter	Min	Typ	Max	Unit	Test Conditions
V _{BAT}	Voltage Input	2.0	3.7	5.5	V	—
HPVDD	APA Power supplyVoltage	2.2	3.7	5.5	V	—
IOVDD	Voltage output	2.0	3.0	3.4	V	V _{BAT} = 4.2V, 10mA loading
	Loading current	—	—	100	mA	IOVDD=3.3V@V _{BAT} ≥ 3.6V
V _{LVD}	Voltage input	1.8	2.5	2.5	V	Low-Voltage Detection of IOVDD

3.3 IO Input/Output Electrical Logical Characteristics

Table 3-3

GPIO input characteristics						
Symbol	Parameter	Min	Typ	Max	Unit	Test Conditions
V _{IL}	Low-Level Input Voltage	-0.3	—	0.3* IOVDD	V	IOVDD = 3.0V
V _{IH}	High-Level Input Voltage	0.7* IOVDD	—	IOVDD+0.3	V	IOVDD = 3.0V
High Voltage Resistant IO input characteristics						
Symbol	Parameter	Min	Typ	Max	Unit	Test Conditions
V _{IL}	Low-Level Input Voltage	-0.3	—	0.3* IOVDD	V	IOVDD = 3.0V
V _{IH}	High-Level Input Voltage	0.7* IOVDD	—	+5V	V	IOVDD = 3.0V
Resistant IO output characteristics						
Symbol	Parameter	GPIO		Typ	Unit	Test Conditions
V _{OL}	0.1*IOVDD Drive current	PA0~PA12 PD0~PD3		HD=1 : -7 HD=2 : -22 HD=3 : -27	mA	IOVDD = 3.0V

V_{OL}	0.1*IOVDD Drive current	PB0~PB3	-7	mA	IOVDD = 3.0V
	0.1*HPVDD Drive current APA IO total current limit of 400mA	APAN APAP	-400		VBAT=3.7V
V_{OH}	0.9*IOVDD Drive current	PA0~PA12 PD0~PD3	HD=1 : 7 HD=2 : 24 HD=3 : 56	mA	IOVDD = 3.0V
		PB0~PB3	7		
	0.9*HPVDD Drive current APA IO total current limit of 400mA	APAN APAP	400		VBAT=3.7V

3.4 Internal Resistor Characteristics

Table 3-4

Port	Internal Pull-Up Resistor	Internal Pull-Down Resistor	Comment
PA0~PA12,PB0~PB3,PD0~PD3	10K	200K	1. PA0,PB2 default pull up 2. PA6~PA9,FSPG default pull down 3. Internal pull-up/pull-down resistance accuracy $\pm 20\%$

3.5 Audio APA Characteristics

Table 3-5

Parameter	MODE	Min	Typ	Max	Unit	Test Conditions	
Frequency Response		20	—	20K	Hz	$R_L=10K, VBAT=3.7V$	
Output Swing	Diff (N to P)	—	1.57	—	Vrms	$R_L=4\Omega$	$f=1kHz/0dB$ VBAT=3.7V
		—	1.83	—	Vrms	$R_L=8\Omega$	
		—	2.22	—	Vrms	$R_L=10K$	
	Single-ended	—	1.11	—	Vrms	$R_L=10K$	
	Diff (N to P)	—	0.99	—	Vrms	$R_L=4\Omega$	$f=1kHz/0dB$ VBAT=2.4V
		—	1.17	—	Vrms	$R_L=8\Omega$	
		—	1.44	—	Vrms	$R_L=10K$	
	Single-ended	—	0.72	—	Vrms	$R_L=10K$	
Output power	Diff (N to P)	—	0.62	—	W	$R_L=4\Omega$	$f=1kHz/0dB$
		—	0.42	—	W	$R_L=8\Omega$	VBAT=3.7V
		—	0.25	—	W	$R_L=4\Omega$	$f=1kHz/0dB$
		—	0.17	—	W	$R_L=8\Omega$	VBAT=2.4V
	Single-ended	—	0.72	—	Vrms	$R_L=10K$	
THD+N	Diff (N to P)	—	-31	—	dB	$R_L=4\Omega$	$f=1kHz/0dB$ A-Weighted VBAT=3.7V
		—	-35	—	dB	$R_L=8\Omega$	
		—	-75	—	dB	$R_L=10K$	
	Single-ended	—	-70	—	dB	$R_L=10K$	
	Diff (N to P)	—	-31	—	dB	$R_L=4\Omega$	$f=1kHz/0dB$ A-Weighted VBAT=2.4V
		—	-36	—	dB	$R_L=8\Omega$	
		—	-73	—	dB	$R_L=10K$	
	Single-ended	—	-70	—	dB	$R_L=10K$	

S/N	Diff (N to P)	—	97	—	dB	$R_L=4\Omega$	f=1kHz/0dB A-Weighted VBAT=3.7V
		—	97	—	dB	$R_L=8\Omega$	
		—	95	—	dB	$R_L=10K$	
	Single-ended	—	75	—	dB	$R_L=10K$	f=1kHz/0dB A-Weighted VBAT=2.4V
		—	94	—	dB	$R_L=4\Omega$	
	Diff (N to P)	—	94	—	dB	$R_L=8\Omega$	
		—	88	—	dB	$R_L=10K$	
		—	72	—	dB	$R_L=10K$	
Dynamic Range	Diff (N to P)	—	88	—	dB	$R_L=4\Omega$	f=1kHz/-60dB A-Weighted VBAT=3.7V
		—	88	—	dB	$R_L=8\Omega$	
		—	86	—	dB	$R_L=10K$	
	Single-ended	—	75	—	dB	$R_L=10K$	f=1kHz/-60dB A-Weighted VBAT=2.4V
		—	87	—	dB	$R_L=4\Omega$	
	Diff (N to P)	—	87	—	dB	$R_L=8\Omega$	
		—	85	—	dB	$R_L=10K$	
		—	74	—	dB	$R_L=10K$	
	Single-ended	—	74	—	dB	$R_L=10K$	

4 Package Information

4.1 QSOP28

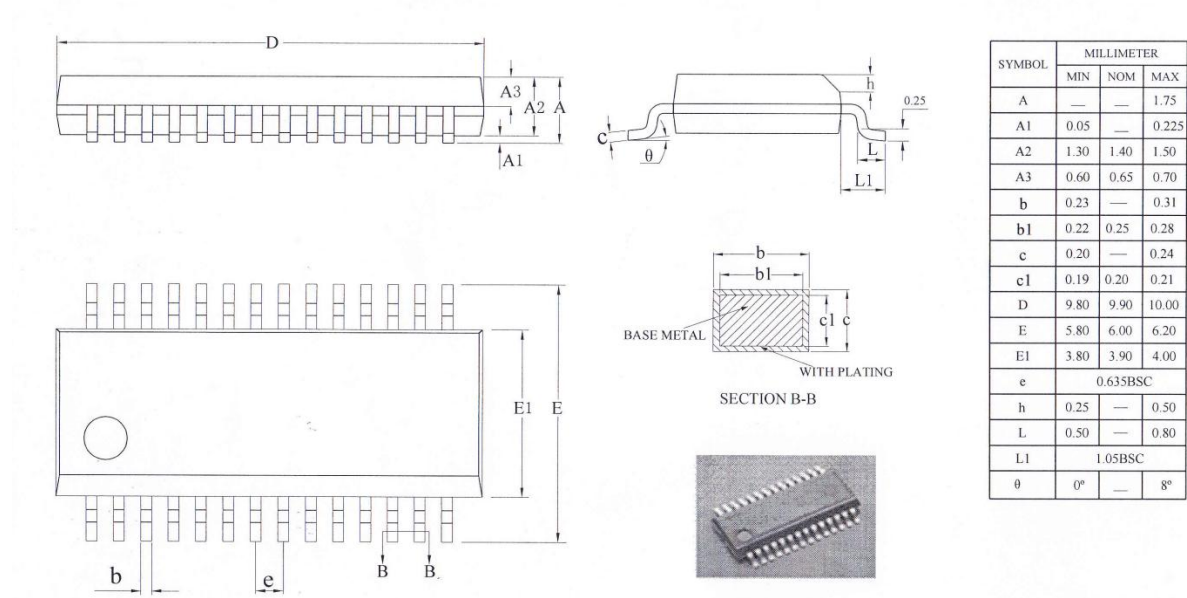
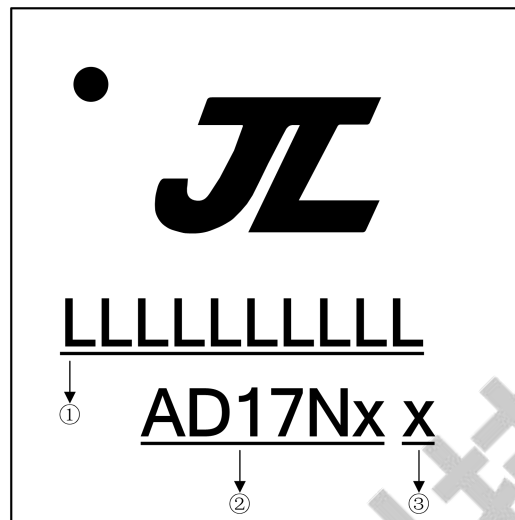


Figure 4-1 AD177A0 Package

5 IC Marking Information



① LLLLLLLLLL : Production Batch

② AD17Nx : Chip Model

③ Built-in flash size

0: No Flash Memory

2: 2Mbit Flash

4: 4Mbit Flash

8: 8Mbit Flash

6: 16Mbit Flash

3: 32Mbit Flash

6 Solder-Reflow Condition

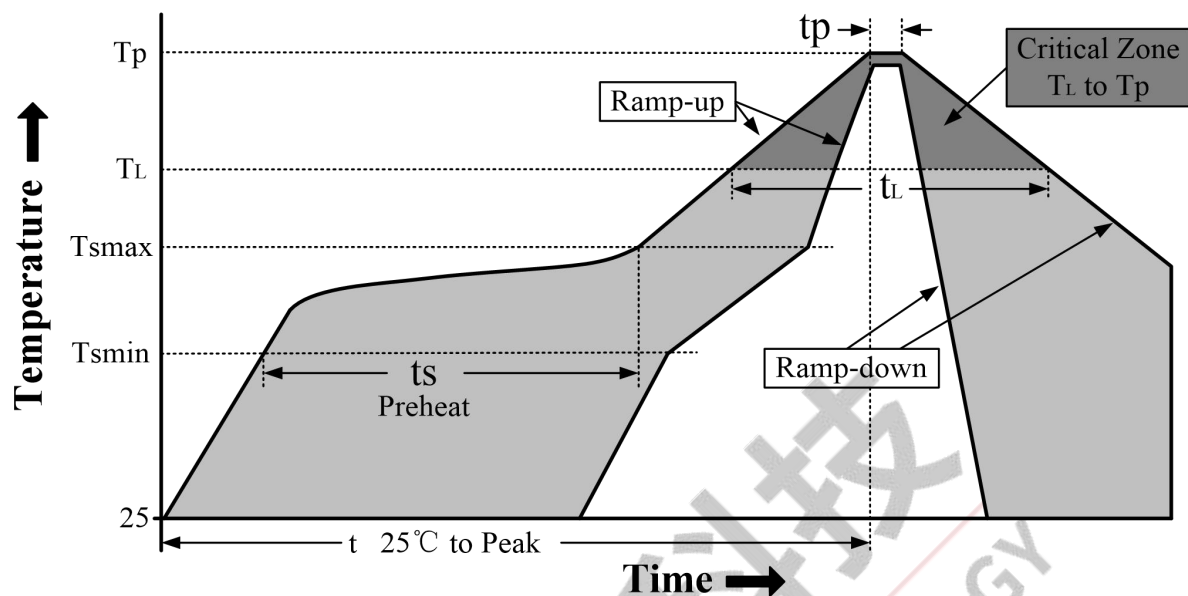


Figure 6-1 Classification Reflow Profile

Classification Profiles

Table 6-1

Profile Feature		Sn-Pb Eutectic Assembly	Pb-Free Assembly
Preheat/ Soak	Temperature Min (T_{smin})	100 °C	150 °C
	Temperature Max (T_{smax})	150 °C	200 °C
	Time (t_s) from (T_{smin} to T_{smax})	60-120 seconds	60-180 seconds
Average ramp-up rate (T_{smax} to T_p)		3 °C/second max	3 °C/second max
Liquidous temperature (T_L)		183 °C	217 °C
Time (t_L) maintained above T_L		60-150 seconds	60-150 seconds
Peak package body temperature (T_p)		See Table 6-2.	See Table 6-3.
Time within 5°C of actual Peak Temperature (t_p)		10-30 seconds	20-40 seconds
Ramp-down rate (T_p to T_L)		6 °C/second max.	6 °C/second max.
Time 25 °C to peak temperature		6 minutes max.	8 minutes max.

Note 1: All temperatures refer to topside of the package, measured on the package body surface.

Note 2: Time within 5°C of actual peak temperature (t_p) specified for the reflow profiles is a “supplier” minimum and “user” maximum.

SnPb - Classification Temperature

Table 6-2

Package Thickness	Volume mm ³ < 350	Volume mm ³ ≥ 350
<2.5 mm	240 +0/-5 °C	225 +0/-5 °C
≥ 2.5 mm	225 +0/-5 °C	225 +0/-5 °C

Pb-free - Classification Temperature **Table 6-3**

Package Thickness	Volume mm ³ < 350	Volume mm ³ 350 - 2000	Volume mm ³ > 2000
< 1.6mm	260 °C	260 °C	260 °C
1.6 mm - 2.5mm	260 °C	250 °C	245 °C
> 2.5mm	250 °C	245 °C	245 °C

7 Revision History

Date	Revision	Description
2023.07.13	V1.0	Initial Release.

